

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2834308

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	JOHN A. PITNEY	04/24/2014
	MANABU HAMANO	04/25/2014
RECEIVING PARTY DATA		
Name:	SUNEDISON SEMICONDUCTOR PTE. LTD. (UEN201334164H)	
Street Address:	80 ROBINSON ROAD, #02-00	
City:	SINGAPORE	
State/Country:	SINGAPORE	
Postal Code:	068898	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	13828926
CORRESPONDENCE DATA		
Fax Number:	(314)612-2307	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	314-621-5070	
Email:	USpatents@armstrongteasdale.com	
Correspondent Name:	RICHARD A. SCHUTH (MEMC)	
Address Line 1:	ARMSTRONG TEASDALE LLP	
Address Line 2:	7700 FORSYTH BOULEVARD, SUITE 1800	
Address Line 4:	ST. LOUIS, MISSOURI 63105	
ATTORNEY DOCKET NUMBER:	28744-4113 (130002.1)	
NAME OF SUBMITTER:	RICHARD A. SCHUTH	
SIGNATURE:	/Richard A. Schuth/	
DATE SIGNED:	04/29/2014	
Total Attachments: 4		
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ASSIGNMENT

WHEREAS, We John A. Pitney of St. Peters, Missouri, and Manabu Hamano of Utsunomiya City, Tochigi Prefecture, Japan, have invented an improvement in GAS DISTRIBUTION PLATE FOR CHEMICAL VAPOR DEPOSITION SYSTEMS AND METHODS OF USING SAME and have executed an application for a United States patent based thereon filed March 14, 2013, assigned Serial No. 13/828,926;

AND, WHEREAS, SunEdison Semiconductor Pte. Ltd. (UEN201334164H), a company incorporated under the laws of Singapore and having its registered address at 80 Robinson Road, #02-00, Singapore 068898 (hereinafter referred to as "ASSIGNEE") is desirous of acquiring certain rights thereunder;

NOW, THEREFORE, for one dollar and other good and valuable consideration, receipt of all of which is hereby acknowledged, we have agreed to and do hereby sell, assign and transfer unto said ASSIGNEE the entire right, title and interest in and throughout the United States of America (including its territories and dependencies) and all countries foreign thereto in and to said invention, said United States application, any other United States applications (including provisional, non-provisional, divisional, continuing, or reissue applications) based in whole or in part on said United States application or in whole or in part on said invention, any foreign applications based in whole or in part on any of the aforesaid United States applications or in whole or in part on said invention, and any and all patents (including extensions thereof) of any country which have been or may be granted on any of the aforesaid applications or on said invention or any part thereof;

TO BE HELD AND ENJOYED by said ASSIGNEE, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by us had no sale and assignment of said interest been made;

AND We hereby authorize and request the Commissioner of Patents of the United States of America to issue any and all United States patents which may be granted upon said United States applications or any of them, or upon said invention or any part thereof, to said ASSIGNEE;

AND We hereby jointly and severally agree for ourselves and for our respective heirs, executors and administrators, to execute without further consideration any further lawful documents and any further assurances, and any provisional, non-provisional, divisional, continuing, reissue, or other applications for patents of any country, that may be deemed

necessary by said ASSIGNEE fully to secure to said ASSIGNEE its interest as aforesaid in and to said invention or any part thereof, and in and to said several patents or any of them;

AND We hereby jointly and severally covenant for ourselves and our respective legal representatives that we have granted no right or license to make, use or sell said invention, to anyone except said ASSIGNEE, that prior to the execution of this deed our right, title and interest in said invention had not been otherwise encumbered, and that we have not executed and will not execute any instrument in conflict herewith.

IN WITNESS WHEREOF, this assignment has been executed by ASSIGNORS and duly authorized representatives of ASSIGNEE.

9/24/14
Date

John A. Pitney
John A. Pitney

STATE OF Missouri)
COUNTY OF St. Charles)

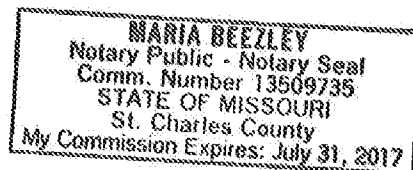
On this 24 day of April, 2014, before me, a Notary Public, personally appeared John A. Pitney to me known to be the person described in and who executed the foregoing assignment and acknowledged that he executed same as his free act and deed.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal the date and year last above written.

Maria Beezley
Notary Public

My Commission Expires:

July 31, 2017



28744-4113 (130002.1)

IN WITNESS WHEREOF, this assignment has been executed by ASSIGNORS and
duly authorized representatives of ASSIGNEE.

Apr 28/2014
Date

Manabu Hamano
Manabu Hamano

O. Yoshimura
Witness

Yukio Okumura
Witness

For and on behalf of SunEdison Semiconductor Pte. Ltd. (UEN201334164H).

Sally Townsley
Name Sally Townsley
Title v.p. and General Counsel
SunEdison Semiconductor Pte. Ltd.

Date 4/29/14

STATE OF Missouri }
COUNTY OF St. Charles }

On this 29 day of April, 2014, before me, a Notary Public, personally appeared Sally Townsley to me known to be the person described in and who executed the foregoing assignment and acknowledged that he executed same as his free act and deed.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal the date and year last above written.

Erika Ziadah
Notary Public

My Commission Expires:

July 20, 2014

